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RESPONSE UNDER 37 CFR 1.116
EXPEDITED PROCEDURE
EXAMINING GROUP 1700

PATENT
Attorney Docket No. 98124X205487
Client Reference No. 98124

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Wang et al.

Application No. 09/636,161

Art Unit: 1765

Filed: August 10, 2000

Examiner: Lynette T. Umez-Eronini

For: POLISHING SYSTEM AND METHOD
OF ITS USE

RESPONSE TO OFFICE ACTION

Commissioner for Patents
Box AF
Washington, D.C. 20231

Dear Sir:

In response to the Office Action dated January 14, 2003, please consider the following remarks.

REMARKS

The Present Invention

The present invention relates to a polishing system and composition for use in polishing a substrate, particularly a multi-layer substrate that includes a first metal layer and a second layer. Claims 1-6, 8, 9, 16-27, and 32-35 currently are pending. However, claim 2 has been withdrawn from consideration by the Office as being directed to a non-elected species.

Summary of Examiner Interview

Applicants thank Examiner Umez-Eronini for the courtesies extended to applicants' representatives, John Kilyk, Jr. and Robert M. Lanning, during the telephonic interview of February 25, 2003. The Section 103 rejection was discussed, consistent with the remarks set forth herein.